



02 0 73

% 6(7 RSSHU 7UD VFHLYHU

02 0 73 RSSHU)3 WUD VFHLYHU

SK VL FODDHLUWHU IIXHWRU % 6(7

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RUDW WLVWHEDEIDUR HFWR VLVFK

FRWURKOKHJJK % 6(.5IRU DG

60., IRU % 6(77KRSSHU)3 WUD VFHLYHUJIKGFORPSOLIDWKK((

VWDGDWFRHWWRUNWKLVRXJWUDGVRJPHIEHSURJUDPWRG

RSHUDWSHJRGDXWRHJRWLWIKWDRYHUWLVHGFDSDELOLWLHV

02 0 73 RSSHU)3 WUD VFHLYHUJIKGFORPSOLIDWKK

EVDGDOORVNSHFHHPHWH,WWHDDEOHVGLPHVRIOLHLEIROLW

1HWRUNKLSPIGWVLJIGIRGDWFWHUISDFCHLWWRPLHIDSSLWDO

02 0 73 RSSHU)3 7UD VFHLYHUJIKGFORPSOLIDWKK

6)306 KLFKDEH DFFHLWIKGURMV YLDWKHMHUDDO((3520

SURWRKOKVLFDDOVDFFHVYHDVHLLDWDGGUHVIRUDULWH

DG IRDUHDWISURWRHWRVWR,2 %ULGJH VHFWR



Features

- 10Gbps Link up to 100 Meters with Cat 6a/7 Cable
- IEEE 802.3az Compliant
- SFF-8431 and SFF-8432 MSA Compliant
- Detailed Product Information in EEPROM
- Access to Physical Layer IC via 2-wire Serial Bus
- I2C to MDIO Bridge (IEEE 802.3 Clause 45)
- Hot-pluggable SFP Footprint
- Compliant with SFP MSA
- Fully Metallic Enclosure for Low EMI
- Compact RJ-45 Connector Assembly
- Compliant with RoHs.
- +3.3V Single Power Supply
- Temperature Range 0°C to +70°C

Application

- 10Gbps Ethernet over Category 6a/7 Cable
- Distributed multi-processing
- High speed I/O for file server or high-end workstation
- Switch/Router to Switch/Router Link

Ordering Information

PART NUMBER	Product Name
MOD-M10GTP	10G Copper SFP

Absolute Maximum Ratings

PARAMETER	SYMBOL	MIN	MAX	UNITS	NOTE
Storage Temperature	T_s	-45	90	°C	
Storage Humidity	H_s	5	95	%	

Recommended Operating Conditions

PARAMETER	SYMBOL	MIN	MAX	UNITS	NOTE
Operating Temperature	T	0	70	°C	Case Temperature
Operating Humidity	H_o	10	85	%	
Supply Voltage	V_{cc}	3.135	3.465	V	Typ. 3.3V
Surge Current	I_{surge}		30	mA	Hot Plug

Cable Length Operating Conditions

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNITS	NOTE
10Gbps @2M Cat7	I		615		mA	(1)
10Gbps @35M Cat7	I		650		mA	(1)
10Gbps @65M Cat7	I		830		mA	(1), (2), (3)
10Gbps @100M Cat7	I		880		mA	(1), (2), (4)
1Gbps @100M Cat6a	I		375		mA	(1)
100Mbps @100M Cat6a	I		225		mA	(1)

Note:

- (1) 25 DegC, measurement after network link up.
- (2) Recommend used @ DataCenter switch with air flow/temperature control
- (3) 30M + "RJ-45 to RJ-45 adaptor" + 35M.
- (4) Single 100M cable only.

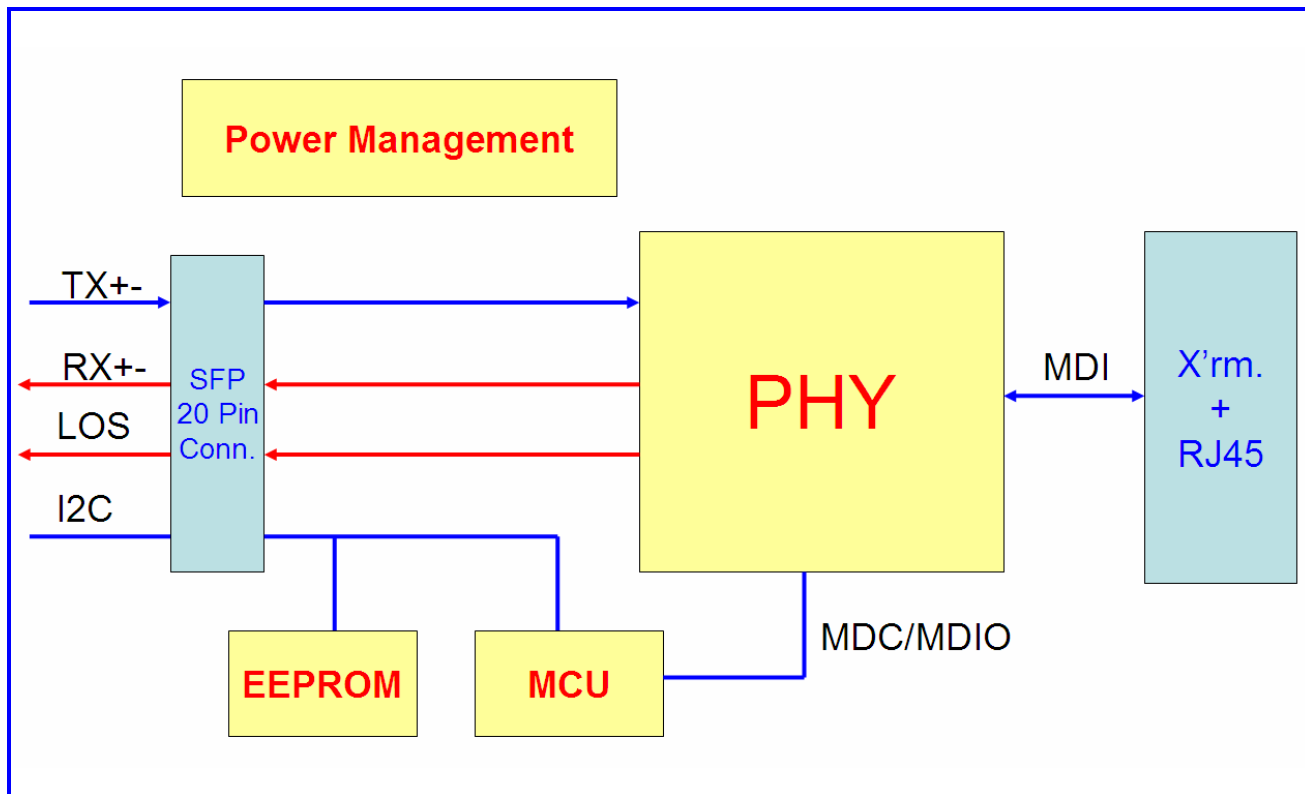
Electrical Characteristics

PARAMETER	SYMBOL	MIN	TYP.	MAX	UNITS	NOTE
Transmitter						
Data Input differential Voltage	$V_{D, TX}$	180			mV	(1)
Differential Input Impedance	Z_{TX}		100		Ohm	
Transmitter Disable Input-High	V_{Dish}		N/A		V	Not implement
Transmitter Disable Input-Low	V_{DISL}		N/A		V	Not implement
Receiver						
Data Output Differential Voltage	$V_{D, RX}$	350			mV	(3)
Differential Output Impedance	Z_{RX}		100		Ohm	
LOS Output Voltage – High	V_{SDHL}	2.4		V_{cc}	V	(2)
LOS Output Voltage – Low	V_{SDL}	0		0.5	V	(2)

Note:

- (1) Internally AC coupled to PHY chip.
- (2) Pull up to VCC with a 4.7K – 10K Ohm resistor on host Board
- (3) Internally AC coupled, but requires a 100 Ohm differential termination at MAC side.

Block Diagram of Transceiver



LOS Function

The SFP MSA specification defines a pin called LOS to indicate loss of signal to the motherboard. This should be pulled up with a 4.7K to 10K resistor. Pull up voltage between 2.0V and $V_{cc-T/R}+0.3V$. When high, this output indicates link fail. Low indicates normal operation. In the low state, the output will be pulled to $<0.8V$.

Termination Circuits

Inputs to the transceiver are AC coupled and internally terminated through 50 ohms. These modules can operate with LVPECL or CML logic levels. The input signal must have at least an 180mV differential peak-to-peak signal swing. Output from the receiver section of the module is also AC coupled and is expected to drive a 50 ohm load. Different termination strategies may be required depending on the particular Serializer/Deserializer chip set used. The transceiver is designed with AC coupled data inputs and outputs to provide the following advantages:

Close positioning of SERDES with respect to transceiver; allows for shorter line lengths and at high speeds reduces EMI. Minimize number of external components. Internal termination reduces the potential for un-terminated stubs which would otherwise increase jitter and reduce transmission margin.

Subsequently, this affords the customer the ability to optimally locate the SERDES as close to the transceiver as possible and save valuable real estate. At 10Gbps rates this can provide a significant advantage resulting in better transmission performance and accordingly better signal integrity.

Power Coupling

A suggested layout for power and ground connections is given in Figure 1 below. Connections are made via separate voltage and ground planes. The mounting posts are at case ground and should not be connected to circuit ground. The ferrite bead should provide a real impedance of 50 to 100 ohms at 100 to 1000 MHz. Bypass capacitors should be placed as close to the 20 pin connector as possible.

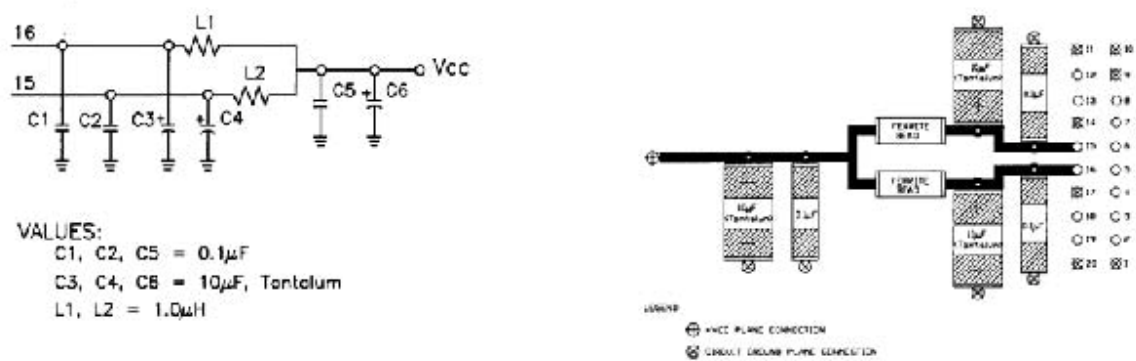


Figure 1: Suggested Power Coupling

Serial Communication Protocol

MOD-M10GTP support the 2-wire serial communication protocol defined in the SFP MSA. These SFP use a 128 byte EEPROM with an address of 0xA0. The physical layer IC can also be accessed via the 2-wire serial bus at address 0xAC/0xAD. See “I2C to MDIO Bridge” section.

EEPROM Serial ID Memory Contents

Accessing Serial ID Memory uses the 2 wire address 10100000 (A0H). Memory Contents of Serial ID are shown in Table 1.

Table 1 Serial ID Memory Contents

Addr.	Size (Bytes)	Name of Field	Hex	Description
0	1	identifier	03	SFP or SFP+
1	1	Ext.Identifier	04	GBIC/SFP function is defined by two-wire interface ID only
2	1	Connector	22	RJ45
3-10	8	Transceiver	XX XX XX XX XX XX	Transceiver Code
11	1	Encoding	00	
12	1	BR(Nominal)	64	10Gbps
13	1	Rate Identifier	00	Unspecified
14	1	Length(SMFm)-km	00	N/A
15	1	Length(SMF)	00	N/A
16	1	Length(50µm)	00	N/A
17	1	Length(62.5µm)	00	N/A
18	1	Length(cable)	21	33(units of meters)
19	1	Length(OM3)	00	N/A
20-35	16	Vendor name	XX XX XX XX XX XX XX 20 20 20 20 20 20 20 20 20	Vendor name (ASCII)
36	1	Transceiver	00	Unallocated
37-39	3	Vendor OUI	XX XX XX	Vendor OUI
40-55	16	Vendor PN	XX XX XX XX XX XX XX XX XX XX XX XX XX XX XX XX	Transceiver part number
56-59	4	Vendor rev	XX XX XX XX	Vendor rev
60-61	2	Wavelength	00	0nm
62	1	Unallocated	00	Unallocated
63	1	CC_BASE	Check Sum (Variable)	Check code for Base ID Fields
64-65	2	Options	00 12	RATE_SELECT functionality is implemented
66	1	BR	00	max
67	1	BR	00	min
68-83	16	Vendor SN	41 34 32 30 33 30 30 34 20 20 20 20 20 20 20	Serial Number of transceiver (ASCII). For example“A4203004”.
84-91	8	Date code	XX XX XX XX XX XX XX XX	Manufacture date code
92	1	Diagnostic Monitoring Type	00	N/A
93	1	Enhanced Options	00	N/A
94	1	SFF-8472 Compliance	00	Digital diagnostic function not included or undefined
95	1	CC_EXT	Check Sum (Variable)	Check sum for Extended ID Field.
96-127	32	Vendor Specific	Read only	Depends on customer information

Note: The “XX” byte should be filled in according to practical case. For more information, please refer to the related document of SFP Multi-Source Agreement (MSA).

I2C to MDIO Bridge

MOD-M10GTP has MCU inside to bridge host I2C to communicate with PHY MDIO interface. The I2C at slave address 0xAC for a write and 0xAD for a read.

MDIO write sequence : 6 bytes I2C frame are required.

- 1st byte : 0xAC (8bits)
- 2nd byte : 0b'000 + DEVAD (5 bits)
- 3~4 bytes : Register Address (16 bits)
- 5~6 bytes : Write Data (16 bits)

MDIO read sequence : 7 bytes I2C frame are required.

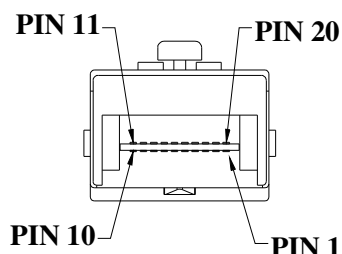
- 1st byte : 0xAC (8bits)
- 2nd byte : 0b'001 + DEVAD (5 bits)
- 3~4 bytes : Register Address (16 bits)
- Delay >1 mS (Important: for MCU access PHY through MDIO)**
- 5th byte : 0xAD (8bits)
- 6~7 bytes : Read Data (16 bits)

Example:

Write 0x55AA to DEVAD 1 Register 0xA820																		
S	1	0	1	0	1	1	0	0	ACK	0	0	0	0	0	0	0	1	ACK
	1	0	1	0	1	0	0	0	ACK	0	0	1	0	0	0	0	0	ACK
	0	1	0	1	0	1	0	1	ACK	1	0	1	0	1	0	1	0	ACK
P																		
Read 0x8542 from DEVAD 1 Register 0x0003																		
S	1	0	1	0	1	1	0	0	ACK	0	0	1	0	0	0	0	1	ACK
	0	0	0	0	0	0	0	0	ACK	0	0	0	0	0	0	1	1	ACK
Delay > 1mS for MCU access PHY MDIO																		
S	1	0	1	0	1	1	0	1	ACK	1	0	0	0	0	1	0	1	ACK
	0	1	0	0	0	0	1	0	NAK	P								
	Master		Slave		S	Start		P	Stop									

Connection Diagram

Pin-Out



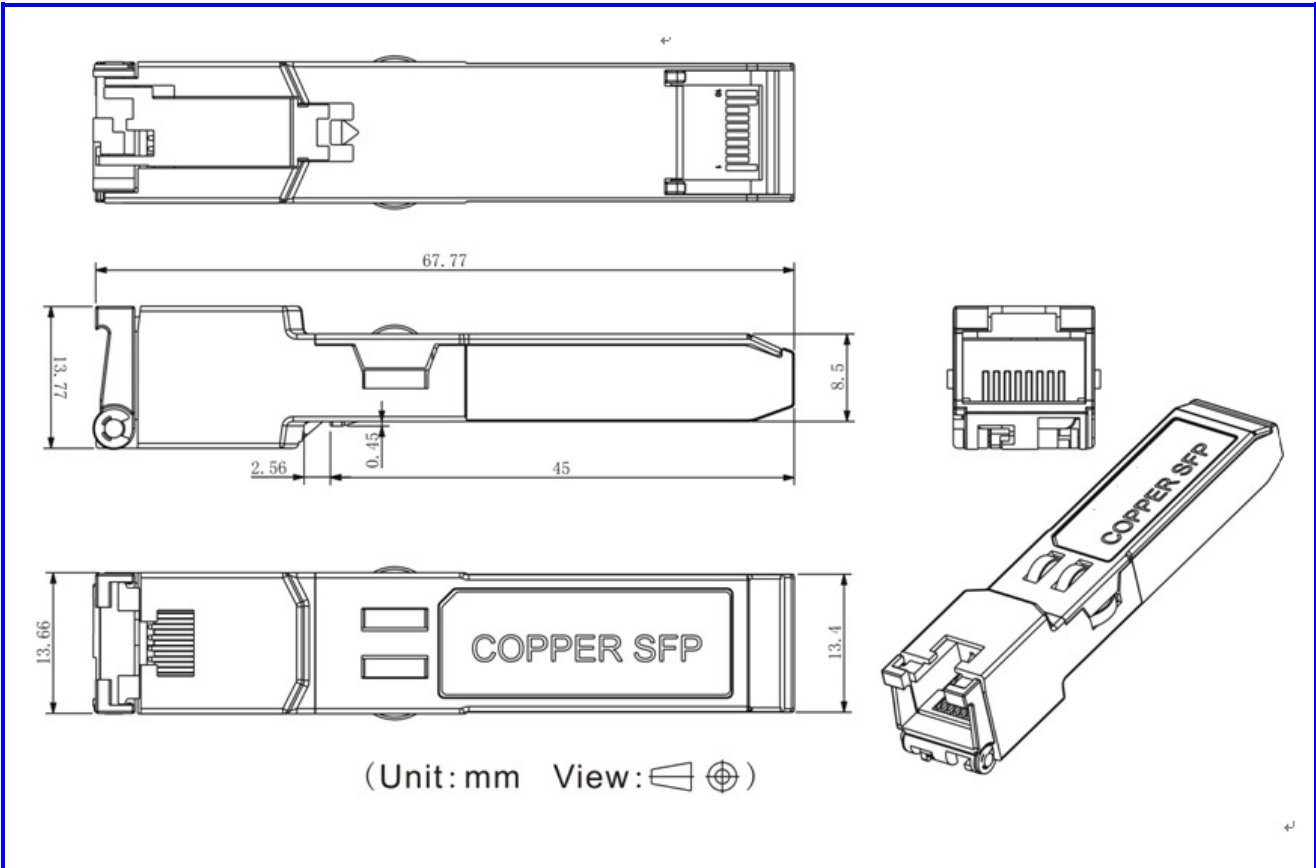
Pin	Signal Name	Function	NOTES
1	VeeT	Transmitter Ground	VeeT and VeeR are connected in SFP.
2	TX_FAULT	Transmitter Fault Indication	Not Implemented. Tied to VeeT in SFP.
3	TX_DISABLE	Transmitter Disable	Not Implemented. Floating in host.
4	MOD DEF (2)	Module Definition 2	Data Line for Serial ID.
5	MOD DEF (1)	Module Definition 1	Clock Line for Serial ID.
6	MOD DEF (0)	Module Definition 0	Tied to Vee in SFP.
7	RATE SELECT	Not Implemented	Not implemented.
8	LOS	Loss of Signal	See LOS option.
9	VeeR	Receiver Ground	VeeT and VeeR are connected in SFP.
10	VeeR	Receiver Ground	VeeT and VeeR are connected in SFP.
11	VeeR	Receiver Ground	VeeT and VeeR are connected in SFP.
12	RD-	Inverted Received Data out	AC coupled 100 ohm differential high speed data lines.
13	RD+	Non-Inverted Received Data out	AC coupled 100 ohm differential high speed data lines.
14	VeeR	Receiver Ground	VeeT and VeeR are connected in SFP.
15	VccR	Receiver Power	VccR and VccT are connected in SFP.
16	VccT	Transmitter Power	VccR and VccT are connected in SFP.
17	VeeT	Transmitter Ground	VeeT and VeeR are connected in SFP.
18	TD+	Non-inverted Data In	AC coupled 100 ohm differential high speed data lines.
19	TD-	Inverted Data In	AC coupled 100ohm differential high speed data lines
20	VeeT	Transmitter Ground	Veet and VeeR are connected in SFP

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Notes:

1. TX Fault is not used and is always tied to ground.
2. TX Disable as described in the MSA is not applicable to the 10GBASE-T module.
3. Mod-Def 0,1, 2. These are the module definition pins. They should be pulled up with a 4.7-10 K resistor on the host board to a supply less than $VCCT + 0.3\text{ V}$ or $VCCR + 0.3\text{ V}$.
4. RD-/+ : These are the differential receiver outputs. They are ac coupled 100 Ohm differential lines which should be terminated with 100 ohm differential at the user SerDes. The ac coupling is done inside the module and is thus not required on the host board. The voltage swing levels are compatible with CML and LVPECL voltage swings.
5. VCCR and VCCT are the receiver and transmitter power supplies. They are defined as $3.3\text{ V} \pm 5\%$ at the SFP connector pin.
6. TD-/+ : These are the differential transmitter inputs. They are ac coupled differential lines with 100 Ohm differential termination inside the module. The ac coupling is done inside the module and is thus not required on the host board. The inputs levels are compatible with CML and LVPECL voltage swings.

Drawing Dimensions



Mating of SFP Transceiver to SFP Host Board Connector

The pads on the PCB of the SFP transceiver shall be designed for a sequenced mating as follows: First mate: Ground contacts. Second mate: Power contacts. Third mate: Signal contacts The SFP MSA specification for a typical contact pad plating for the PCB is 0.38 micrometers minimum hard gold over 1.27 micrometers minimum thick nickel. To ensure the long term reliability performance after a minimum of 50 insertion removal cycles, the contact plating of the transceiver is 0.762 micron (30 micro-inches) over 3.81 micron (150 micro-inches) of Ni on Cu contact pads.

RJ45 Connector

RJ45 connector shall support shielded and unshielded cables. Also, the connector is mechanically robust enough and designed to prevent loss of link, when the cable is positioned or moves in different angles. The connector shall pass the “wobble” RJ45 connector operational stress test. During the test, after the cable is plugged in, the cable is moved in circle to cover all 360 deg in the vertical plane, while the data traffic is on. There shall be no link or data loss.